



Changshu Talent
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ESDA6V1L

Features

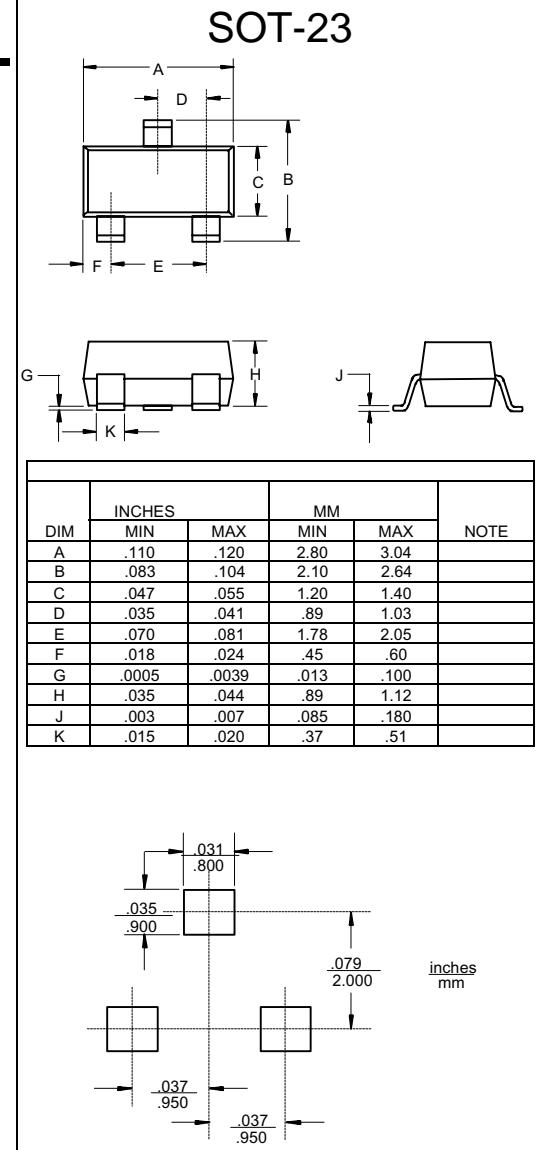
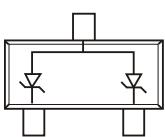
- Dual Transil Array For ESD Protection
- 2 Unidirectional Transil Functions
- Low leakageCurrent: $I_{Rmax}<20\text{ }\mu\text{A}$ at V_{WM}
- 300W peak pulse power (8/20 us)
Epoxy meets UL 94 V-0 flammability rating
Moisture Sensitivity Level 1

**6.1Volts
ESD Protection
Device**

Maximum Ratings

Parameter	Symbol	Limits	unit
Electrostatic discharge MIL STD 883C-Method 3015-6 IEC61000-4-2 air discharge IEC61000-4-2 contact discharge	V_{PP}	25 16 9	KV KV KV
Peak pulse power 8/20us	P_{PP}	300	W
Junction temperature	T_j	150	°C
Storage temperature range	T_{stg}	-55~+150	°C
Maximum lead temperature For soldering during 10s	T_L	260	°C

Pin Configuration-Top View

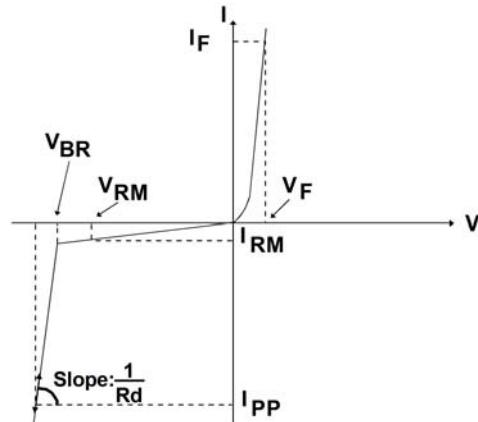


ESDA6V1L



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter
V_{WM}	Stand-off voltage
V_{BR}	Breakdown voltage
V_{CL}	Clamping voltage
I_{RM}	Leakage current
I_{PP}	Peak pulse current
αT	Voltage temperature coefficient
C	Capacitance
R_d	Dynamic resistance
V_F	Forward voltage drop



Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Breakdown voltage	$I_R=1.0\text{mA}$	V_{BR}	6.1	6.65	7.2	V
Leakage current	$V_{WM}=5.25\text{V}$	I_R	-	-	20	μA
Capacitance	0V bias	C	-	140	-	pF
Forward voltage drop	$I_F=200\text{mA}$	V_F	-	-	1.25	V

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TYPICAL CHARACTERISTICS

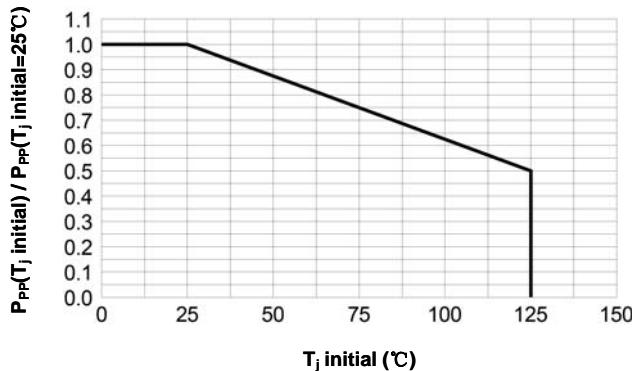


Fig.1: Peak power dissipation vs. initial junction temperature

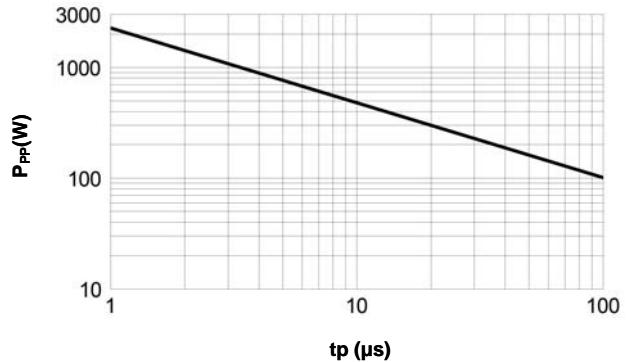


Fig.2: Peak pulse power vs. exponential pulse duration
($T_j \text{ initial} = 25^\circ\text{C}$)

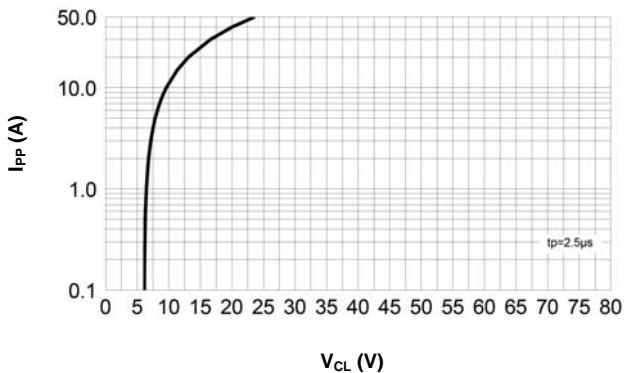


Fig.3: Clamping voltage vs. peak pulse current
($T_j \text{ initial} = 25^\circ\text{C}$, rectangular waveform $t_p = 2.5\mu\text{s}$)

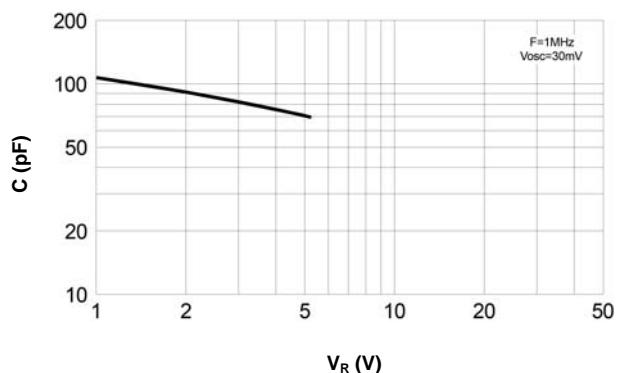


Fig.4: Capacitance vs. reverse applied voltage
(typical values)

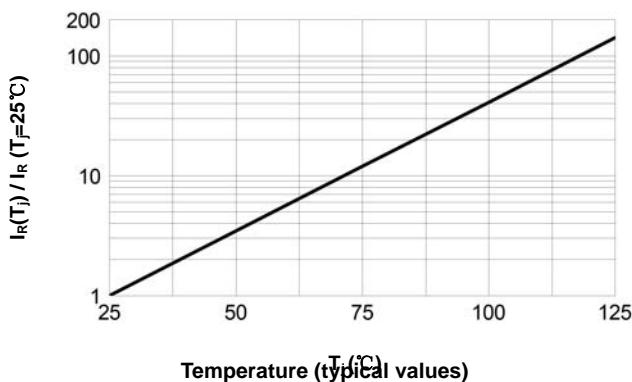


Fig.5: Relative variation of leakage current vs. junction

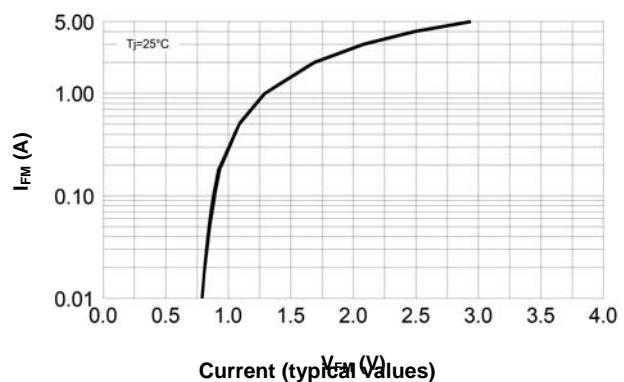


Fig.6: Peak forward voltage drop vs. peak forward